

ABSTRACT**CONTACTING MEANS AND METHOD FOR CONTACTING ELECTRICAL COMPONENTS**

The present invention provides a method for connecting at least two components, in which a sintering preform is used. This preform comprises a carrier having a surface that has at least one structuring element that contains hardened paste, wherein the hardened paste contains (a) metal particles having a coating that contains at least one organic compound, and (b) at least one sintering aid selected from the group consisting of (b1) organic peroxides, (b2) inorganic peroxides, (b3) inorganic acids, (b4) salts of organic acids, wherein the organic acids have 1 – 4 carbon atoms, (b5) esters of organic acids, wherein the organic acids have 1 – 4 carbon atoms, and (b6) carbonyl complexes, and the surface of the carrier having the hardened paste not being reactive to the constituents of the paste.